

**Services List**  
**Global ETS, LLC - Headquarters**

<b>Testing Categories</b>	<b>Code</b>	<b>Testing Items</b>
Incoming Packaging Inspection	GR101	Incoming - Documentation and Packaging Inspection
External Visual Inspection	GV101	External Visual inspection - Leads Repairs
External Visual Inspection	GV102	External Visual inspection - Detailed
External Visual Inspection	GV103	External Visual inspection - General Without Magnification
External Visual Inspection	GV104	External Visual inspection - Sorting
External Visual Inspection	GV105	Mechanical Inspection - Dimensions
External Visual Inspection	GV106	Mechanical Inspection - Dimensions Contactless
External Visual Inspection	GV307	Mechanical inspection - Parts weight measurement
X-Ray / XRF	GX101	X-Ray - Standard 2D
X-Ray / XRF	GX102	X-Ray - 2D_Tray _ Automated (High Quantity) with AI Inspection
X-Ray / XRF	GX203	X-Ray - 2D_Reels _ Automated (High Quantity) wih AI Inspection
X-Ray / XRF	GX104	XRF - RoHS 1.0 / 6 Elements
X-Ray / XRF	GX105	XRF - Lead Finish Analysis
X-Ray / XRF	GX106	XRF, Material Composition
X-Ray / XRF	GX307	XRF - Lead Finish Thickness
X-Ray / XRF	GX308	XRF - Rohs 2.0 / 10 Elements
X-Ray / XRF	GX309	XRF - Rohs 3.0 / 10 Elements
X-Ray / XRF	GX210	XRF - Hexavalent Chromium Analysis
Destructive Test / Decapsulation	GD112	Delid/Decapsulation - Thermomechanical
Destructive Test / Decapsulation	GD313	Delid/Decapsulation - Acid
Destructive Test / Decapsulation	GD314	Delid/Decapsulation - Bonding Wires Inspection
Destructive Test / Decapsulation	GD315	Lead - Cross Section
Destructive Test / Decapsulation	GD109	Re-Surfacing _Scrape Test
Destructive Test / Decapsulation	GD101	Solderability Test - Dip & Look Method
Destructive Test / Decapsulation	GD103	Solderability Test - BGA Oven Reflow Tests
Destructive Test / Decapsulation	GD117	Solderability Test - Lead Preconditioning - Steam Conditioning
Destructive Test / Decapsulation	GD118	Solderability Test - Lead Preconditioning - Dry Bake Conditioning
Destructive Test / Decapsulation	GD305	Solderability Test - Wetting Balance
Destructive Test / Decapsulation	GD306	Solderability Test - Coverage Analysis Inspection (Additional Services)
Destructive Test / Decapsulation	GD107	Solvent Test - Re-Marking _Marking Permanency Test
Destructive Test / Decapsulation	GD110	Solvent Test - Re-Surfacing_1-Methyl 2-Pyrrolidinone (1M2P) Test
Destructive Test / Decapsulation	GD111	Solvent Test - Re-Surfacing_Dynasolve 750 (or equivalent) Test
Destructive Test / Decapsulation	GD115	Solvent Test - Re-Surfacing _Nonaggressive _Acetone Test
Destructive Test / Decapsulation	GD116	Solvent Test - Re-Surfacing _Aggressive _Acetone Test
Destructive Test / Decapsulation	GD316	DPA (Destructive Physical Analysis)
Shipping	GS102	Shipping - Packaging _Baking Services
Shipping	GS106	Shipping - Drop Shipping Domestic
Shipping	GS107	Shipping - Drop Shipping International
Shipping	GS101	Tape and Reeling Services
Electrical	GE101	Electrical - Capacitor Test, at ambient temp.
Electrical	GE102	Electrical - Resistor Test, at ambient temp.
Electrical	GE103	Electrical - Inductor Test, at ambient temp.
Electrical	GE104	Electrical - Impedance Test (Ferrite Beads), at ambient temp.
Electrical	GE105	Electrical - Color dot on all passing devices
Electrical	GE106	Electrical - Curve Trace Testing, at ambient temp.
Electrical	GE207	Electrical - Diode Test, at ambient temp.
Electrical	GE208	Electrical - Transistor Testing - MOSFET (Field Effect Transistors ), at ambient temp.
Electrical	GE209	Electrical - Transistor Testing - BJT (Bipolar Junction Transistors), at ambient temp.

Electrical	GE210	Electrical - Memory testing, at ambient temp.
Electrical	GE211	Electrical - Erase and Blank Checking at ambient temp.
Electrical	GE212	Electrical - SRAM Testing, at ambient temp.
Electrical	GE213	Electrical - Programming services
Electrical	GE214	Electrical - DC at ambient temp.
Electrical	GE314	Electrical - Capacitor Test, over temp.
Electrical	GE315	Electrical - Inductor Test, over temp.
Electrical	GE316	Electrical - Impedance Test (Ferrite Beads), over temp.
Electrical	GE317	Electrical - Diode Test, over temp.
Electrical	GE318	Electrical - Transistor Testing - MOSFET (Field Effect Transistors ), over temp.
Electrical	GE319	Electrical - Transistor Testing - BJT (Bipolar Junction Transistors), over temp.
Electrical	GE320	Electrical - Curve Trace Testing, over temp.
Electrical	GE321	Electrical - Memory testing, over temp.
Electrical	GE322	Electrical - SRAM Testing, over temp.
Electrical	GE324	Electrical - DC Parameters, over temp.
Electrical	GE325	Electrical - Functional Testing, at ambient temp.
Electrical	GE326	Electrical - Functional Testing, over temp.
Electrical	GE327	Electrical - Key Parameters AC, Switching, at ambient temp.
Electrical	GE328	Electrical - Key Parameters AC, Switching, over temp.
Electrical	GE329	Electrical - Key Parameters AC, Switching, Functional at ambient temp.
Electrical	GE330	Electrical - Key Parameters AC, Switching, Functional over temp.
Electrical	GE331	Electrical - Burn-In with Pre- and Post Electrical Tests
Electrical	GE332	Electrical - Thermal Shock with Pre- and Post Electrical Tests
Electrical	GE333	Electrical - JTAG and BSCAN Test
Electrical	GE334	Electrical - FPGA Speed Grade Test at Specify Temp.
Electrical	GE335	Electrical - Thermal Cycle Testing
Electrical	GE336	Electrical - RF testing
Electrical	GE337	Electrical - Temperature Upscreen testing
Electrical	GE359	Electrical - First Article Inspection
Electrical	GE359	Electrical - Thermal Shock
Electrical	GE360	Electrical - LCD Display Testing, at ambient temp.
Electrical	GE361	Electrical - Moisture Resistance
Electrical	GE369	Electrical - QTST - FSC 5961 (Semiconductors) Test
Electrical	GE370	Electrical - QTST- FSC 5962 (Semiconductors) Test
Electrical	GE372	Electrical - Steady-State Temperature-Humidity Bias Life Test
Material	GE340	Materials Analysis - SEM _Scanning Electron Microscope
Material	GE341	Materials Analysis - EDS/EDX _Energy Dispersive Spectroscopy
Material	GE342	Failure Analysis
Material	GE343	Materials Analysis - C-SAM _Scanning Acoustic Microscopy
Material	GE344	Materials Analysis - FTIR Spectroscopy _Material Analysis
Material	GE345	Materials Analysis - FTIR Spectroscopy _Contamination Analysis
Material	GE346	Materials Analysis - Raman Spectroscopy _Material Analysis
Material	GE347	Materials Analysis - Raman Spectroscopy _Contamination Analysis
Material	GE348	Materials Analysis - Body - Cross Section
Material	GE350	Material Analysis - Thermogravimetric analysis(TGA)
Material	GE351	DDPA, Bond Pull
Material	GE352	DDPA, Die Attach
Material	GE357	AM, PEMS - External only
Material	GE358	AM, PEMS - External, Internal and Material (Incremental)
Material	GE368	Material- Particle Impact Noise Detection Test (PIND)
Re-Balling	GT312	Re-balling - Standard
Re-Balling	GT313	Re-balling - Reflow

Re-Balling	GT314	Re-balling - Laser
Re-Balling	GT315	Re-balling - Removing Balls and Cleaning the Substrate
Re-Tinning	GT101	Re-Tinning - Color dot on all tinned devices
Re-Tinning	GT202	Re-Tinning - Rohs to Non Rohs
Re-Tinning	GT203	Re-Tinning - Non Rohs to Rohs
Re-Tinning	GT204	Re-Tinning - SAC305
Re-Tinning	GT205	Re-Tinning - SN63/PB37
Re-Tinning	GT307	Re-Tinning - Stripped and Preconditions
Re-Tinning	GT308	Re-Tinning - Cleanliness Evaluation Test / Ion Chromatography
Re-Tinning	GT309	Re-Tinning - Rohs to Non Rohs
Re-Tinning	GT310	Re-Tinning - Non Rohs to Rohs
Other Services	GO303	Hermeticity Testing